

High density I²C EEPROM with new F9V process



New F9V process addressing customers needs

Industrial



Mobile



Consumer



Volume in high-density EEPROM

Optimized footprint

Competitive pricing

Consumption effectiveness

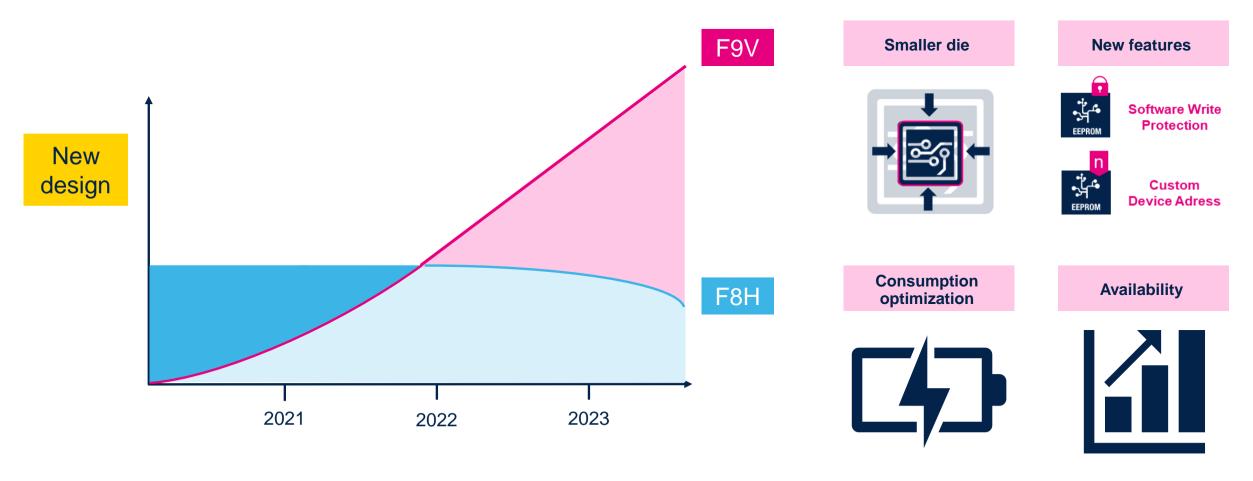
High retention High endurance

+ new features

F9V

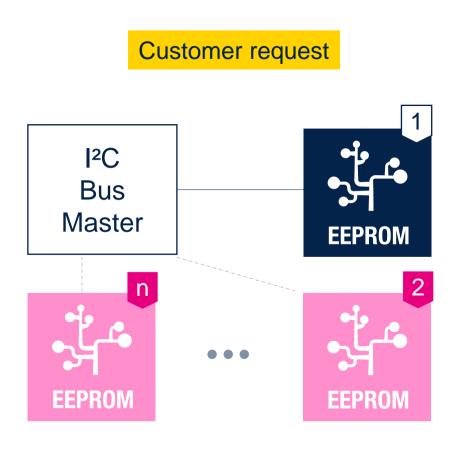


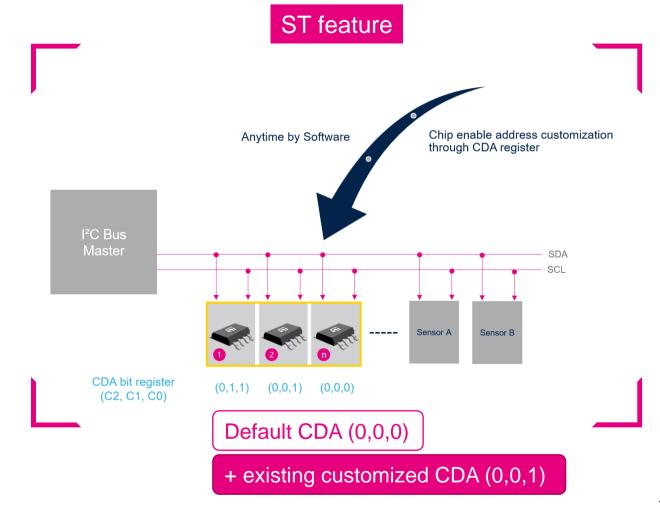
ST Technology roadmap F9V for new design





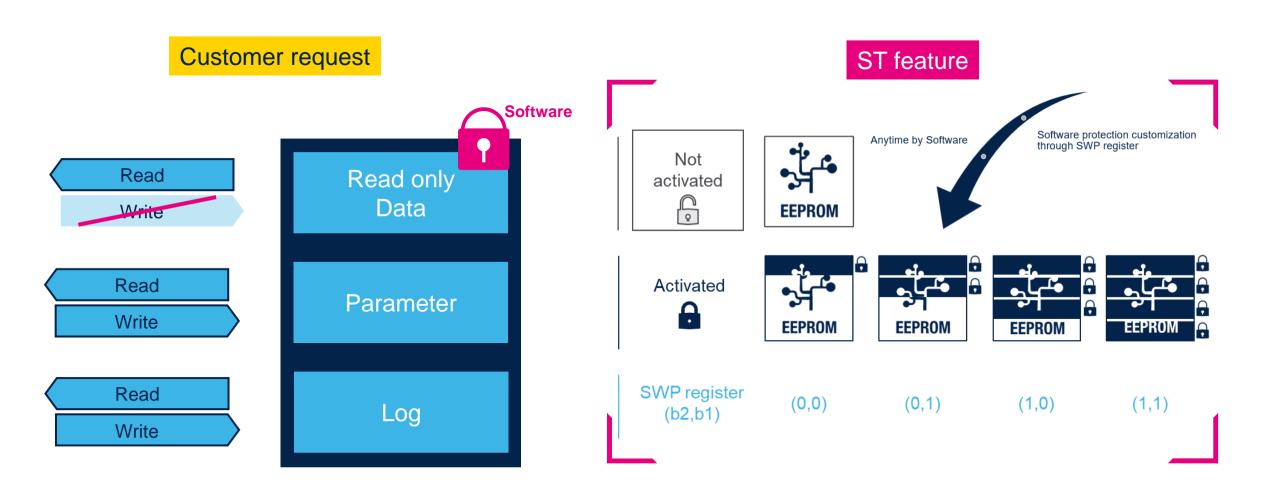
CDA register for multiple EEPROM on same bus







Write Protect Software for data protection





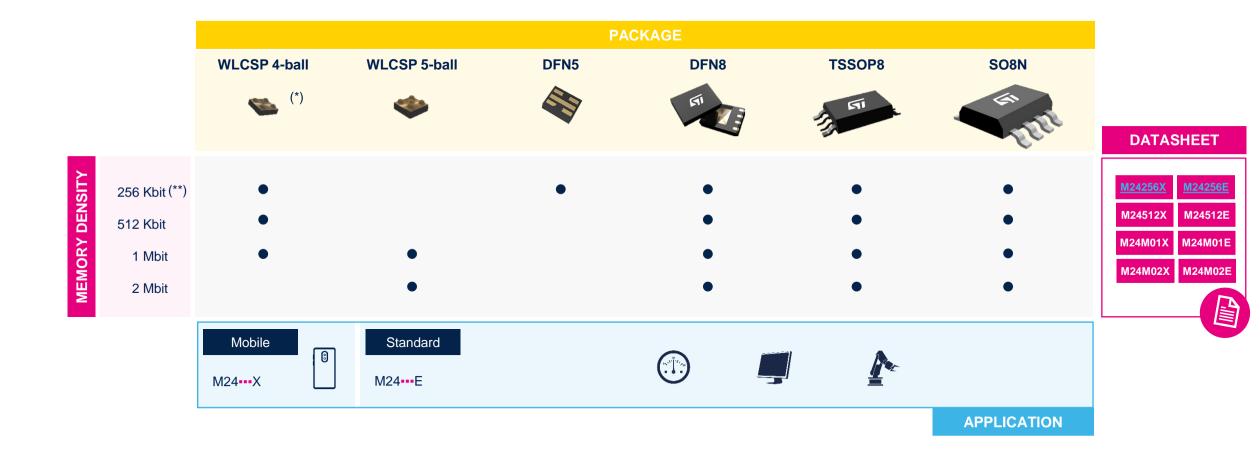
WLCSP designed for mobile Die size reduced

Improved thickness and footprint





F9V process I²C standard EEPROM portfolio





Our technology starts with You



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